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SOT418-2

plastic, heatsink small outline package; 20 leads; low standoff height

25 September 2018

Package information

Package summary

Terminal position code D (double)

Package type descriptive code HSOP20

Package type industry code HSOP20

Package style descriptive code HSOP (heatsink small outline package)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date23-07-2003Manufacturer package codeSOT418

Table 1. Package summary

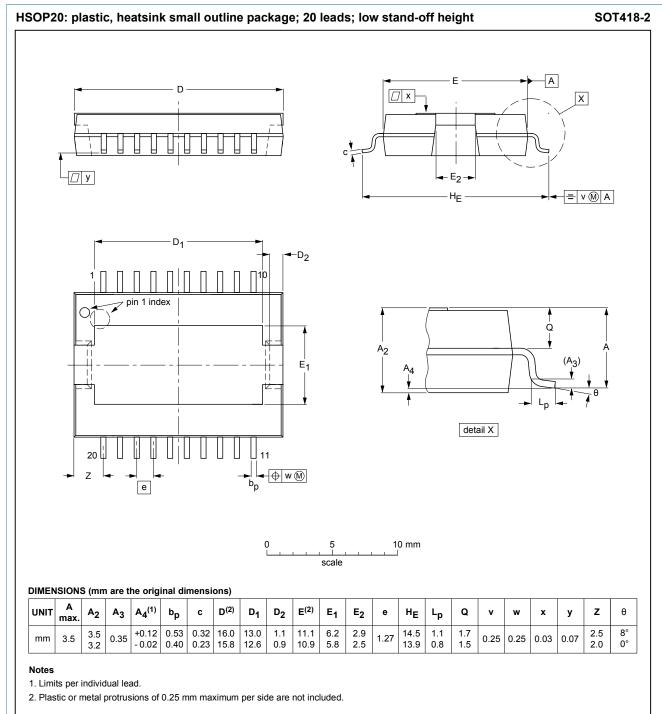
Parameter	Min	Nom	Max	Unit
package length	15.8	15.9	16	mm
package width	10.9	11	11.1	mm
seated height	-	3.5	-	mm
package height	3.2	3.35	3.5	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	20	-	



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2 Package outline



OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT418-2						03-02-18 03-07-23

Figure 1. Package outline HSOP20 (SOT418-2)

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3 Legal information

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